

Patent claims

1. Method for producing electric conductive structures for use in high frequency technology on a conductive structure carrier by executing the following steps: Applying a resist coating to a metal
5 coating of the conductive structure carrier; Structuring the resist coating with the aid of a laser and etching away the areas revealed by the laser, with chemical tin, and amorphous resist or a resist being used for the resist layer of the categories resist series ma-N 2400 from micro resist technology GmbH or a corresponding
10 further development of such a category.
2. Method in accordance with Claim 1, characterized in that an FR 4 carrier material is used as a conductive structure carrier.
3. Method in accordance with Claim 1 or 2, characterized in that at least in an environment of electric conductive structures
15 usable with high-frequency technology at least remaining electrical conductor structures can be removed over large areas.